

LG-T3535RGBA-TD

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REV. : A/1

Approved By:

Checked By:

Prepared By:

LG-T3535RGBA-TD

TOP Full-color LED

Technical Data Sheet

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These products are full-color SMD components with black frame and white refractor, high contrast, which are featured by multiple waterproof performance, good reliability, long lifespan and wide viewing angle. They are designed for outdoor display and decoration applications.

Features:

- Material:

Red	Green	Blue
AlGaInP	InGaN	InGaN
- Encapsulation: Epoxy Resin
- Soldering methods: Pb-Free reflow soldering
- High Luminous Intensity, Low Power Dissipation, Good Reliability and Long Life
- **RoHS**
Complied with RoHS Directive

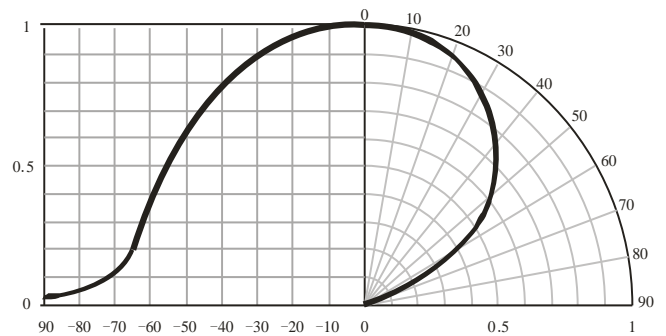
Catalogue

Electrical Characteristics.....

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Typical Characteristics Curves



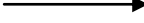
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Packaging (1)

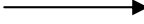
◇ Carrier Tape

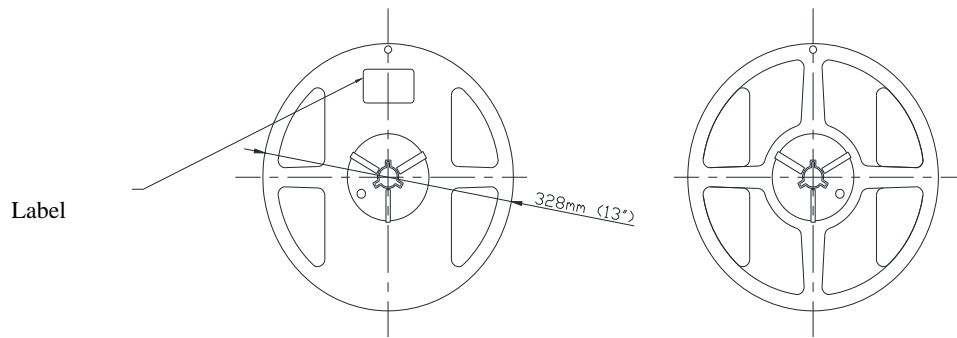


◇ Details Of Carrier Tape

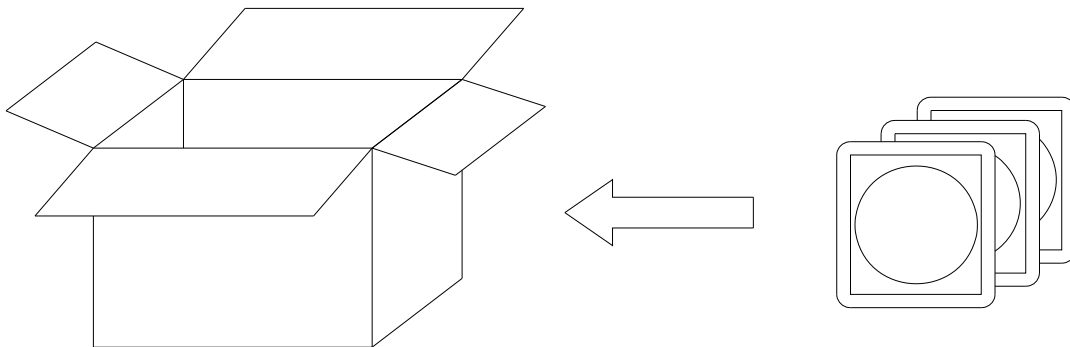
Progressive Direction 

◇ Reel Dimension

Progressive Direction 



✧ · **Cardboard Box**



✧ · **Label Explanation**

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Guideline for Soldering (1)

1.

Hand Soldering

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If manual soldering is used, the use of a soldering iron of less than 25W is recommended. The temperature of the iron must be kept below 315 , with soldering time within 3 seconds and each electrode can be only soldered at one time.

- SMD LED

The epoxy resin of the SMD LED should not contact the tip of the soldering iron.

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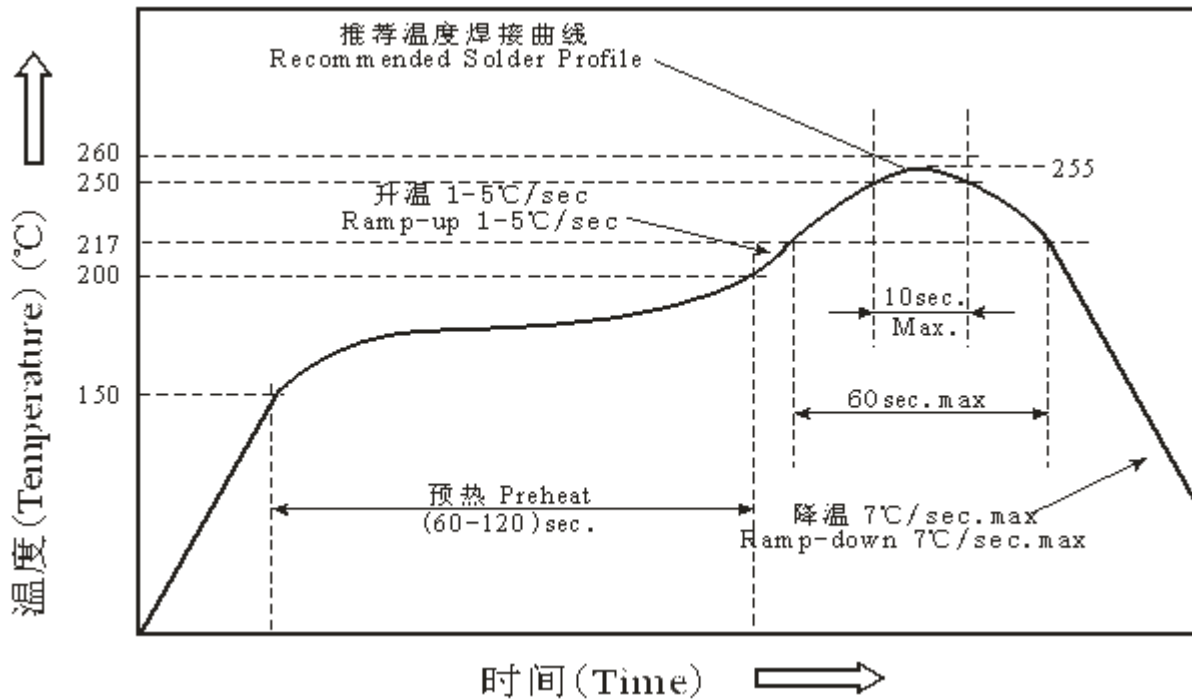
No mechanical stress should be exerted on the resin portion by the tip of the soldering iron.

- 40 LED

Handing of the SMD LED should be done when the temperature of environment is below 40 , in case of LED failures caused by thermal-mechanical stress in condition of high temperature .

2.

Reflow Soldering: Use the conditions shown in the under Figure of Pb-Free Reflow Soldering.





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Guideline for Soldering (2)

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Reflow soldering should not be done more than one time.

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Stress on the LEDs should be avoided during heating in the reflow soldering process.

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After soldering, do not deal with the product before its temperature drop down to room temperature.

3.

Cleaning

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It is recommended that alcohol Anhydrous ethanol be used as a solvent for cleaning after soldering. Cleaning is to go under 30 for 3 minutes or 50 for 30 seconds. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not.

300W

LED

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Ultrasonic cleaning is also an effective way for cleaning. The influence of Ultrasonic cleaning on LED depends on factors such as ultrasonic power. Generally, the ultrasonic power should not be higher than 300W, otherwise it will cause LED damage. Before cleaning, a pre-test should be done to confirm if any damage to LEDs will occur.

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PCB

PCB

*Note: This general guideline may not apply to all PCB designs and configurations of all soldering equipment. The technique in practice is influenced by many factors, it should be specialized base on the PCB designs and configurations of the soldering equipment.

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Such as the reverse current increase rapidly. And it will cause the string light when the screen is black. So please pay attention to controlling the reverse voltage which less than 10V is recommended.

5.

The safe temperature for LEDs working

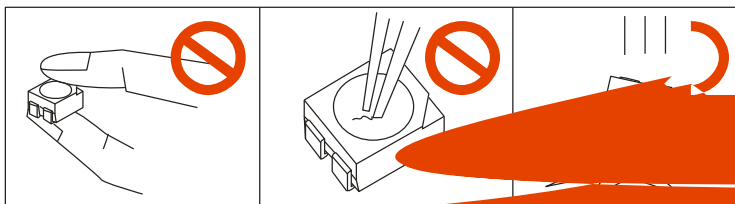
- LED 书 实 再 55 75 are used in hot environment for a long time, they will be disabled easily. When LEDs are used in a high density array, we suggest that the LEDs lower than 75 .

6.

Others

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When handling the product, touching the encapsulation with bare hands will not only contaminate its surface, but also have an effect on its optical characteristics. Excessive force to the encapsulation might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



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